

Results for the Fiscal Year Ended March 31, 2026

Ferrotec Corporation

1. The consolidated results for this fiscal year include the results of consolidated subsidiaries for the period from January 1 to December 31, 2025.
2. This presentation has been prepared for the purpose of providing information regarding the Company's results of operations for the fiscal year ended March 31, 2026 and does not constitute a solicitation to purchase securities issued by the Company. Please ensure that the decision on whether to make an investment in the Company is made at your own risk.
3. These materials were prepared based on information available as of the date of disclosure. All opinions, forecasts and other forward-looking statements are based on management's judgments in accordance with materials available at that time and may be changed without prior notice.



Medium-Term Management Plan – Basic Policy

➤ Updated from the Medium-Term Management Plan disclosed on May 30, 2025

Business growth

- Expand production in Malaysia and other locations to address the Ex-China production needs of Japanese, U.S., and European customers, while strengthening customer engagement in China to achieve growth, as demand for semiconductor-related products continues to grow.
- Pursue growth by expanding the semiconductor, electronic device, and automotive businesses, with a particular focus on AI and data center-related businesses.

Improving profitability & production efficiency

- Improve profitability by expanding production and enhancing efficiency at the Malaysia factories (Kulim and Johor).
- Drive group-wide cost management and reduction through PDCA cycles.
- Pursue improved production efficiency and enhanced competitiveness through digitalization, automation, and AI adoption.
- Advance and strengthen the development of new products and technologies at the research centers of each business, while maintaining rigorous quality control under the principle that “Quality is Everything.”

Strengthening human capital & corporate culture

- Recognize corporate culture as the foundation of the Company, and continue to promote our guiding principles: “Respect customers and employees, value diligence and integrity, act steadily, and pursue innovation.”
- Position human capital as a key management strategy, conduct training in each business, and promote the recruitment and development of talent.

Financial strategy & shareholder returns

- Strengthen shareholder returns by adopting DOE with a minimum level of 3.5%. Flexibly consider share buybacks, taking into account financial conditions and other factors, and aim for a total payout ratio of 50%. Maintain this policy unchanged.
- Divest group assets totaling ¥50.0bn over the period from FY26/3 through FY27/12.
- Carry out share buybacks of up to ¥25.0bn over the period from FY26/12 through FY28/12.

Topics (1): Scaling up production capacity to capture semiconductor-related demand - Malaysia

- Establishing a large-scale mass production base in Malaysia to meet the Ex-China production needs of European and U.S. customers

Malaysia – Kulim Factory No.1



- Customer qualification, the start of mass production and production volume ramp-up are progressing steadily.
- As customer qualification progresses and production volumes increase further, the factory is expected to contribute to earnings going forward.

Malaysia – Kulim Factory No.2



- Building construction is scheduled to be completed in August 2026.
- Operations are expected to commence by the end of 2026.

Topics (2): Scaling up production capacity to capture semiconductor-related demand - China

- Strengthening customer coverage in the Chinese semiconductor market by establishing production facilities near customer sites, capturing domestic substitution demand and expanding sales of high-value-added products in China



Beijing Factory



- Construction commenced in March 2026 and is progressing toward completion of the building in December 2026.
- Operations are scheduled to begin in June 2027.

Shaoxing Factory



- Scheduled to commence operations in summer 2027

Wuhan Factory

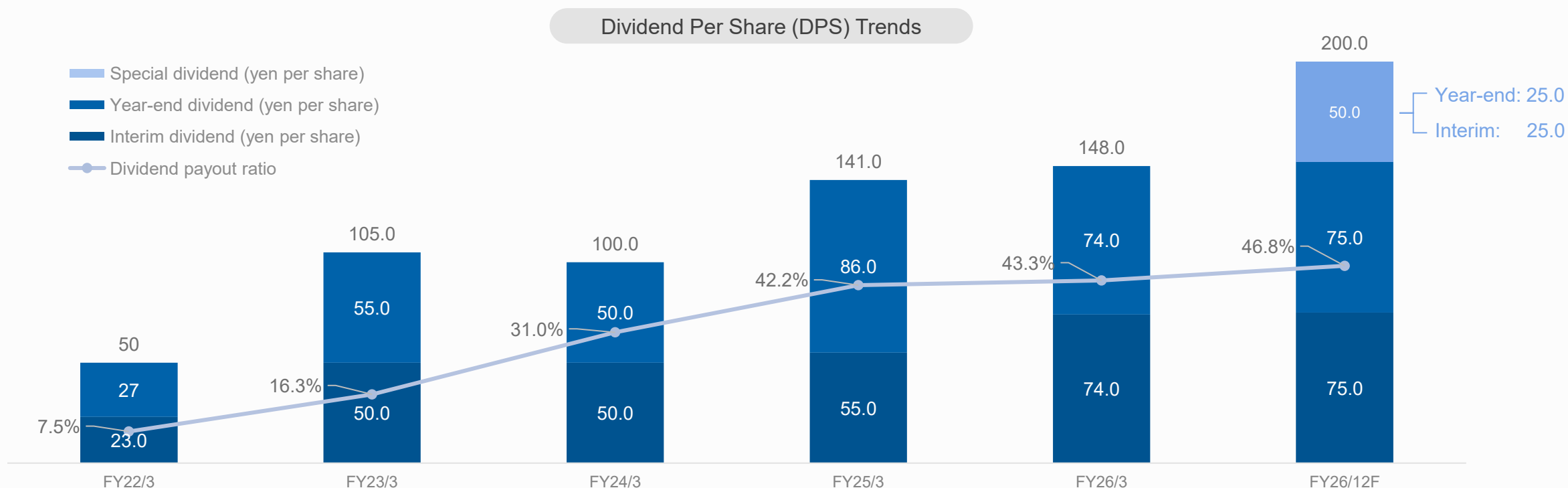


- Equipped with state-of-the-art cleaning lines.
- Scheduled to commence operations in summer 2027

Shareholder Return Policy

- Strengthen shareholder returns by adopting DOE with a minimum level of 3.5%. Flexibly consider share buybacks, taking into account financial conditions, and aim for a total payout ratio of 50%. Maintain this policy unchanged from the previous plan.
- The Company plans to increase dividends, with a full-year dividend of ¥200 per share (ordinary dividend of ¥150 plus special dividend of ¥50; dividend payout ratio of 46.8%).

* For the interim dividend for FY26/12, the record date will be changed from September 30 to June 30, and the interim dividend will be paid based on the new record date.



- 1. Consolidated Financial Summary**
- 2. Consolidated Balance Sheet and Cash Flows**
- 3. Full-Year Earnings Forecast (FY26/12)**
- 4. Medium-Term Management Plan**

1. Consolidated Financial Summary

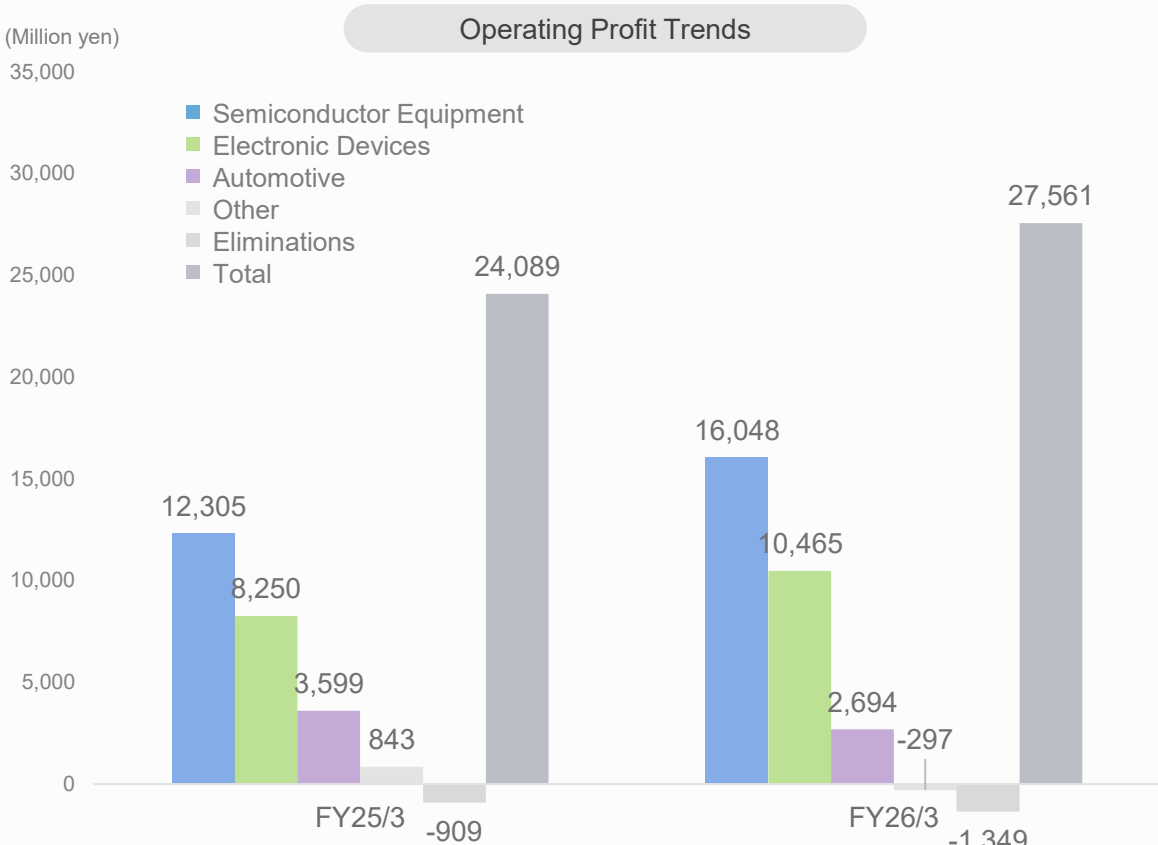
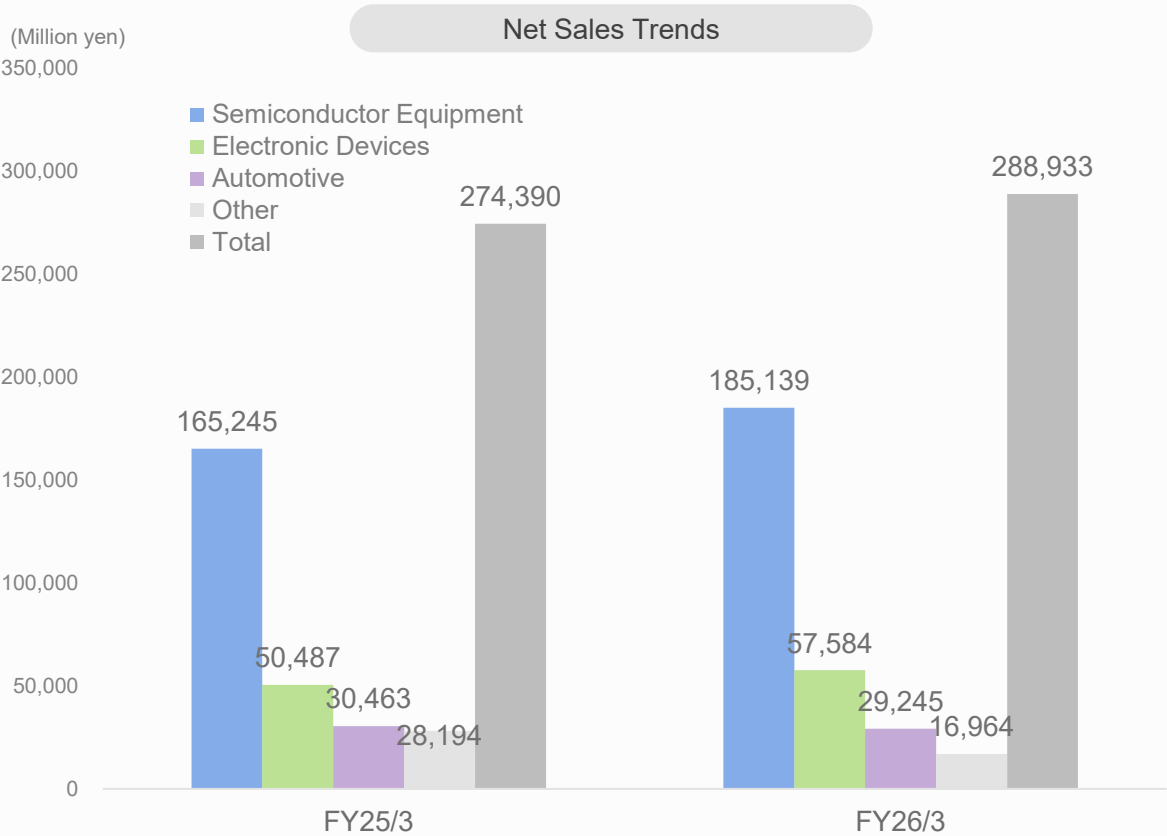
Full-Year Consolidated Financial Summary

- Net sales increased 5% YoY; operating profit increased 14% YoY.
- Profit attributable to owners of parent decreased 5% YoY, impacted by a ¥2.4bn deterioration in foreign exchange gains/losses and an approximately ¥2.0bn increase in income taxes.

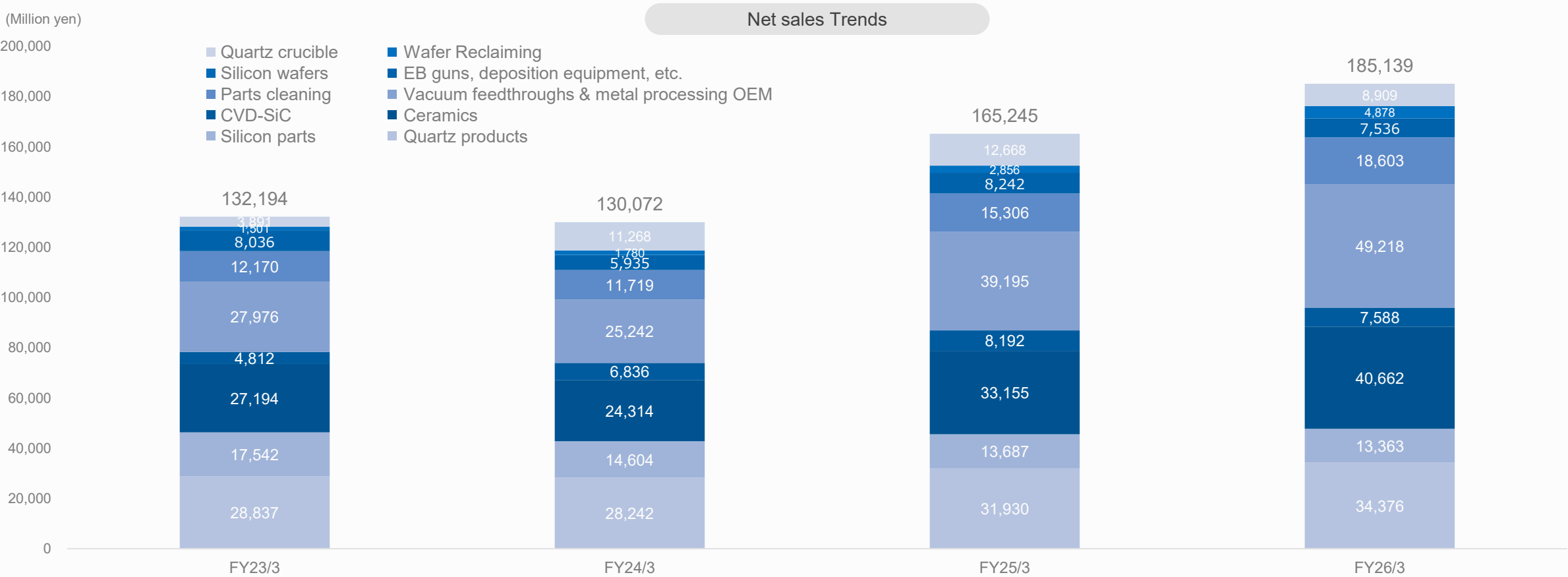
(Millions of yen; unless otherwise stated)	FY26/3 Amount	FY25/3 Amount	YoY change	
			Amount	%
Net sales	288,933	274,390	14,542	5.3%
Cost of sales	207,616	201,029	6,586	3.3%
Gross profit	81,317	73,361	7,955	10.8%
SG&A expenses	53,755	49,271	4,483	9.1%
Operating profit	27,561	24,089	3,471	14.4%
Ordinary profit	26,063	25,558	505	2.0%
Profit attributable to non-controlling interests	3,540	3,607	-66	-1.9%
Profit attributable to owners of parent	14,886	15,692	-806	-5.1%
Depreciation and amortization	27,426	23,672	3,754	15.9%
Exchange rate (average during the period)	USD/JPY	¥149.78	¥152.24	
	RMB/JPY	¥20.87	¥21.12	

Sales and Operating Profit Summary by Segment

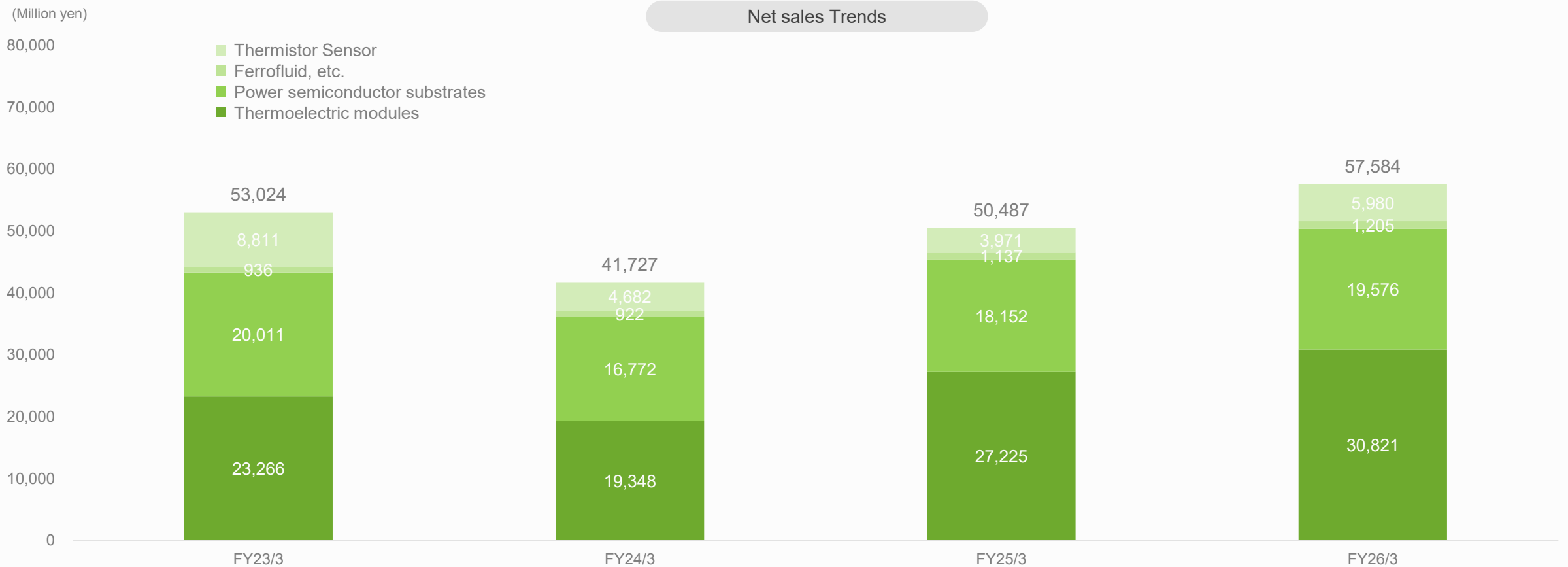
- **Semiconductor Equipment:** Net sales increased 12% YoY to ¥185.1bn; operating profit increased 30% YoY to ¥16.0bn.
- **Electronic Devices:** Net sales increased 14% YoY to ¥57.5bn; operating profit increased 26% YoY to ¥10.4bn.
- **Automotive:** Net sales decreased 4% YoY to ¥29.2bn; operating profit decreased 25% YoY to ¥2.6bn.



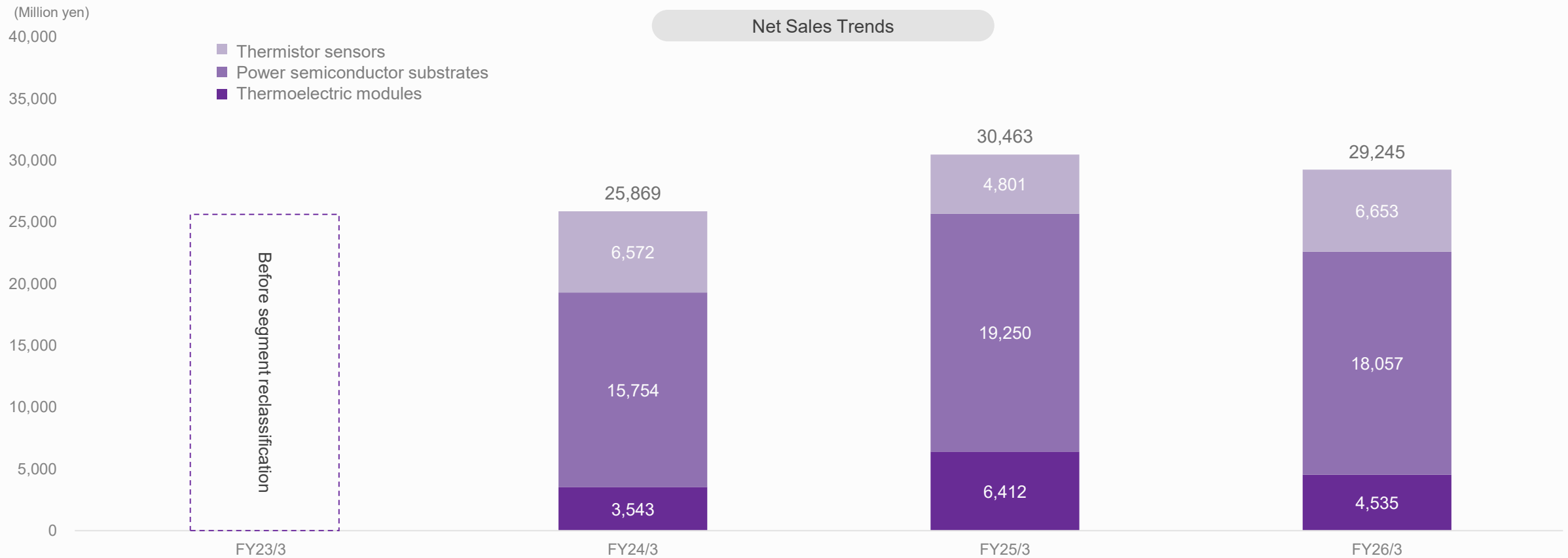
- Captured increased demand driven by production expansion among SPE manufacturers, with particular growth in ceramics, vacuum feedthroughs, and metal processing OEM.
- Driven primarily by increased semiconductor manufacturing activity in China, parts cleaning and wafer reclaiming also grew.



- Sales of thermoelectric modules for optical transceivers expanded, driven by strong investment in generative AI servers.
- Sensor sales increased year-on-year, as Q1 sales were not recorded in the prior year due to the change in fiscal year end at OHIZUMI MFG.



- Demand for power semiconductor substrates for EVs and other applications entered an adjustment phase, resulting in weak sales and profit. Thermoelectric modules also faced headwinds.
- Sensor sales increased year-on-year, as Q1 sales were not recorded in the prior year due to the change in fiscal year end at OHIZUMI MFG.



2. Consolidated Balance Sheet and Cash Flows

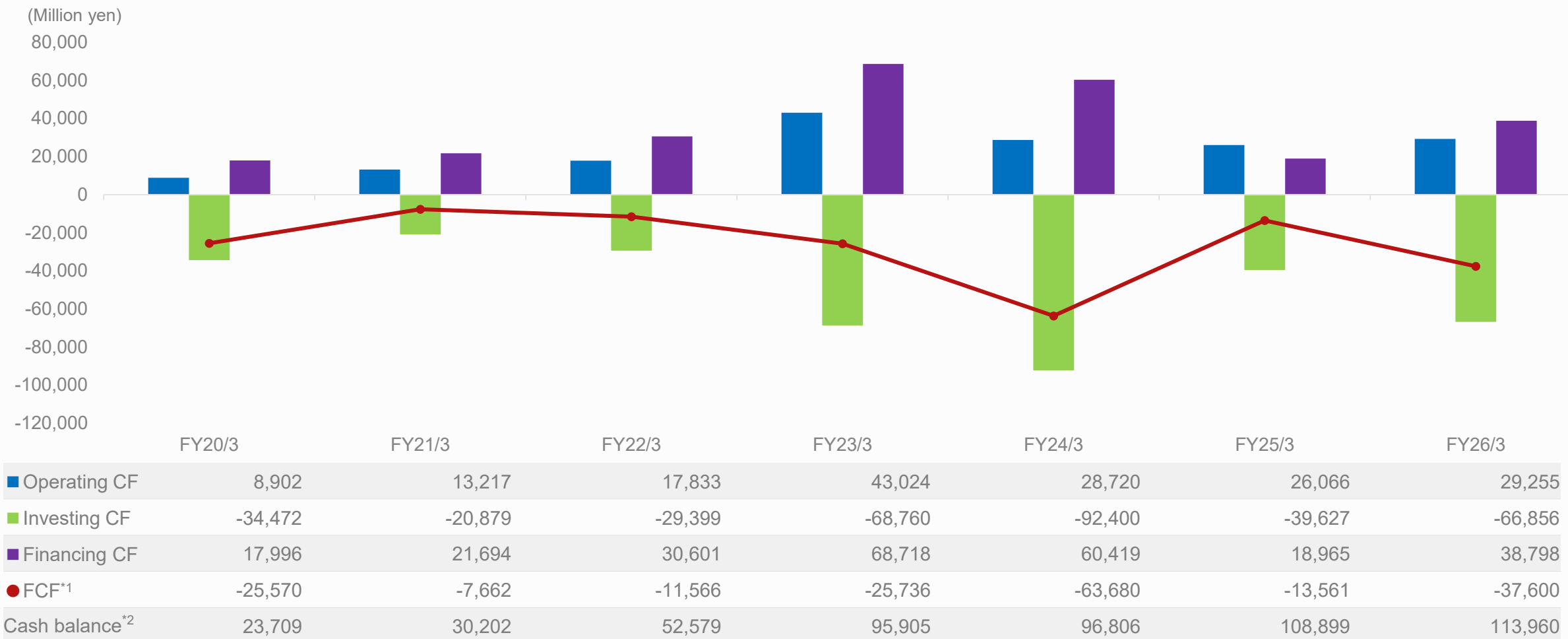
Consolidated Balance Sheet

- **Property, plant and equipment increased by ¥36.0bn and interest-bearing debt increased by ¥40.0bn, primarily due to capital investment in the Malaysia Factory.**

(Millions of yen; unless otherwise stated)	FY25/3-end	FY26/3-end	YoY change
Current assets	295,367	338,977	43,610
Cash and deposits	117,727	129,918	12,191
Notes and accounts receivable - trade	92,608	101,710	9,102
Inventories	72,078	88,309	16,230
Non-current assets	305,226	350,260	45,033
Property, plant and equipment	245,064	281,107	36,043
Total assets	600,593	689,238	88,644
Current liabilities	151,750	163,052	11,301
Non-current liabilities	125,292	164,110	38,817
Total interest-bearing debt	162,296	202,344	40,047
Total liabilities	277,043	327,162	50,119
Net assets	323,549	362,075	38,525
Total liabilities and net assets	600,593	689,238	88,644
Equity ratio	39.4%	37.6%	-1.8 pp
Exchange rate (year-end)	USD/JPY	¥158.18	¥156.56
	RMB/JPY	¥21.67	¥22.36

Cash Flows

- Although operating cash flow increased, investing cash outflows rose due to capital investment in the Malaysia Factory and other projects, resulting in negative free cash flow (FCF).



*1. Operating CF + Investing CF

*2. Balance of cash and cash equivalents at period-end

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3. Full-Year Earnings Forecast (FY26/12)

Change in Fiscal Year-End (April–March → January–December)

- The Board of Directors resolved on May 15 to change the fiscal year end from March to December starting from the next fiscal year, subject to approval at the General Shareholders' Meeting on June 26, 2026.
- The next fiscal year will be a 9-month fiscal period (April–December 2026). However, since our consolidated subsidiaries have a December fiscal year end, their results will cover January–December (12 months), while the parent alone will record April–December (9 months). Therefore, the impact of the 9-month fiscal period on consolidated financial results will be limited.
- From the fiscal year after next, both the parent and subsidiaries will operate on a 12-month fiscal year from January to December 2027.

Schedule Following the Change in Fiscal Year-End

		Jan.	Feb.	Mar.	Apr.	May	Jun.	Jul.	Aug.	Sep.	Oct.	Nov.	Dec.	Next Jan.	Feb.	Mar.
Current FY26/3	Parent				April 2025–March 2026											
	Subs	January 2025–December 2025														
Next FY26/12	Parent				April–December 2026			Q1*	Q2*			Full-year results			Carried forward to the next period	
	Subs	January 2026–December 2026						Q1*	Q2*			Full-year results				
After Next FY27/12	Parent	January 2027–December 2027														
	Subs	January 2027–December 2027														

*Q1 results for the next fiscal year will cover April–June 2026 for the parent (January–June 2026 for the subsidiaries), and Q2 results will cover April–September 2026 for the parent (January–September 2026 for the subsidiaries).

FY26/12 Full-Year Earnings Forecast

- Supported by strong demand in the Semiconductor Equipment segment and continued growth in thermoelectric modules for optical transceivers, we forecast higher sales and profit.

(Millions of yen; unless otherwise stated)	FY26/3 full year		FY26/12 full year	
	Actual	Forecast	YoY (Ref.)	
Net sales	288,933	350,000	21.1%	
Operating profit	27,561	38,000	37.9%	
Ordinary profit	26,063	36,000	38.1%	
Profit attributable to owners of parent	14,886	23,000	54.5%	
CapEx*	54,598	65,000	19.1%	
Depreciation and amortization	27,426	32,172	17.3%	
EBITDA	54,988	70,172	27.6%	
Exchange rate (average during the period)	USD/JPY	¥149.78	¥150.0	
	RMB/JPY	¥20.87	¥21.00	

*CapEx = Total acquisition cost of property, plant, and equipment and intangible assets

Product Sales Summary – FY26/3 Actual and FY26/12 Forecast

(Millions of yen)	FY26/3 Actual	FY26/12 Forecast		■ Notes and outlook
	Full year	Full year	YoY (Ref.)	
Semiconductor Equipment	185,139	222,190	20.0%	Inquiries from U.S. and Chinese customers are increasing rapidly, and the outlook is positive.
Vacuum feedthroughs & metal processing OEM	49,218	68,307	38.8%	Correlated with semiconductor production equipment (SPE) output. Metal processing and equipment assembly are surging.
Quartz products	34,376	38,912	13.2%	Consumables tied to semiconductor production and are also affected by customer inventory adjustments.
Silicon parts	13,363	17,198	28.7%	Inquiries from SPE manufacturers are increasing.
Ceramics	40,662	49,036	20.6%	Correlated with SPE production.
CVD-SiC	7,588	4,416	-41.8%	Impacted by the change in fiscal year-end, mainly because FTJ is the primary operating entity, and by declining demand for certain products.
EB guns, LED deposition equipment, etc.	7,536	7,059	-6.3%	Sluggish demand; sales expected to decline.
Wafer reclaiming	4,878	2,943	-39.7%	To become non-consolidated from July 2026; sales will be excluded from consolidated sales.
Parts cleaning	18,603	22,848	22.8%	Correlated with semiconductor factory operations in China.
Quartz crucibles	8,909	11,471	28.7%	Scaling back PV applications and focusing on semiconductor applications, with recovery expected.
Electronic Device	57,584	73,965	28.4%	Growth expected, led by thermoelectric modules.
Thermoelectric modules	30,821	40,526	31.5%	Sales growth expected for AI-related optical transceivers.
Power semiconductor substrates	19,576	22,511	15.0%	Sales growth expected through expanded product range.
Ferrofluid	1,205	1,534	27.2%	Growth in existing products and new product launches.
Thermistor sensors	5,980	9,394	57.1%	No sales were recorded for January–March in the prior year due to the change in fiscal year-end.
Automotive	29,245	36,135	23.6%	EV market recovering; improvement expected vs. FY26/3.
Thermoelectric modules	4,535	5,846	28.9%	Growing inquiries for automotive products.
Power semiconductor substrates	18,057	22,247	23.2%	Recovery in Chinese EV production expected.
Thermistor sensors	6,653	8,042	20.9%	No sales were recorded for January–March in the prior year due to the change in fiscal year-end. Sales are expected to increase through strengthened sales efforts.
Other	16,964	17,710	4.4%	
Total	288,933	350,000	21.1%	

4. Medium-Term Management Plan

Medium-Term Management Plan KPIs

- Forecasts and plans for FY26/12 and beyond have been revised upward. Although the ROE and ROIC targets for FY28/12 have been lowered, we continue to aim for 15% and 8%, respectively, over the longer term.

(Millions of yen; unless otherwise stated) Figures in parentheses indicate changes from the previous plan.		FY26/3 Actual	FY26/12 Forecast	FY27/12 Plan	FY28/12 Plan
Performance	Net sales	288,933 (+3,933)	350,000 (+10,000)	400,000	450,000
	Operating profit	27,561 (-2,439)	38,000 (+3,000)	48,000 (+1,000)	57,000
	OP margin	9.5%	10.9%	12.0%	12.7%
	Profit	14,886 (-1,114)	23,000 (+3,000)	30,000 (+1,000)	38,000
Capital efficiency	ROE	6.0%			11.0% (-4%)
	ROIC ^{*1}	3.2%			7.0% (-1%)
Financial	Equity ratio	37.6%	40.0%	40.0%	40.0%
	CapEx.	54,598 (-10,402)	65,000 (+20,000)	55,000 (+25,000)	40,000
Shareholder returns	DPS ^{*2} (annual)	¥148.0	¥200.0	Adopt DOE (dividend on equity, based on consolidated shareholders' equity ^{*2}) with a minimum level of 3.5%. Flexibly consider share buybacks, targeting a total payout ratio of 50%.	

*1. Profit attributable to owners of parent / (Interest-bearing debt + Net assets), excluding share acquisition rights and non-controlling interests from net assets

*2. Consolidated shareholders' equity = Share capital + Capital surplus + Retained earnings – Treasury shares. DOE = Total dividends paid ÷ Consolidated shareholders' equity

Medium-Term Management Plan – Basic Policy

➤ Updated from the Medium-Term Management Plan disclosed on May 30, 2025

Business growth

- Expand production in Malaysia and other locations to address the Ex-China production needs of Japanese, U.S., and European customers, while strengthening customer engagement in China to achieve growth, as demand for semiconductor-related products continues to grow.
- Pursue growth by expanding the semiconductor, electronic device, and automotive-related businesses, with a particular focus on AI and data center-related businesses.

Improving profitability & production efficiency

- Improve profitability by expanding production and enhancing efficiency at the Malaysia factories (Kulim and Johor).
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Financial strategy & shareholder returns

- Strengthen shareholder returns by adopting DOE with a minimum level of 3.5%. Flexibly consider share buybacks, taking into account financial conditions and other factors, and aim for a total payout ratio of 50%. Maintain this policy unchanged.
- Divest group assets totaling ¥50.0bn over the period from FY26/3 through FY27/12.
- Carry out share buybacks of up to ¥25.0bn over the period from FY26/12 through FY28/12.

Performance

- FY26/3 net sales ¥288.9bn, operating profit ¥27.6bn, profit attributable to owners of parent ¥14.9bn. Profit growth was constrained due to increased inventory write-downs at new factories and other factors.
- FY26/12 full-year forecast: net sales ¥350.0bn, OP ¥38.0bn, profit attributable to owners of parent ¥23.0bn.

Trends

- As AI-driven semiconductor investment and production continue to gain momentum, progress has been made in addressing the Ex-China production needs of U.S. SPE customers.
- Increased investment and production in China's semiconductor industry are driving growing inquiries for metal processing, ceramics and other products as we advance customer engagement.
- In thermoelectric modules, inquiries for optical communication module applications remain robust.

CapEx

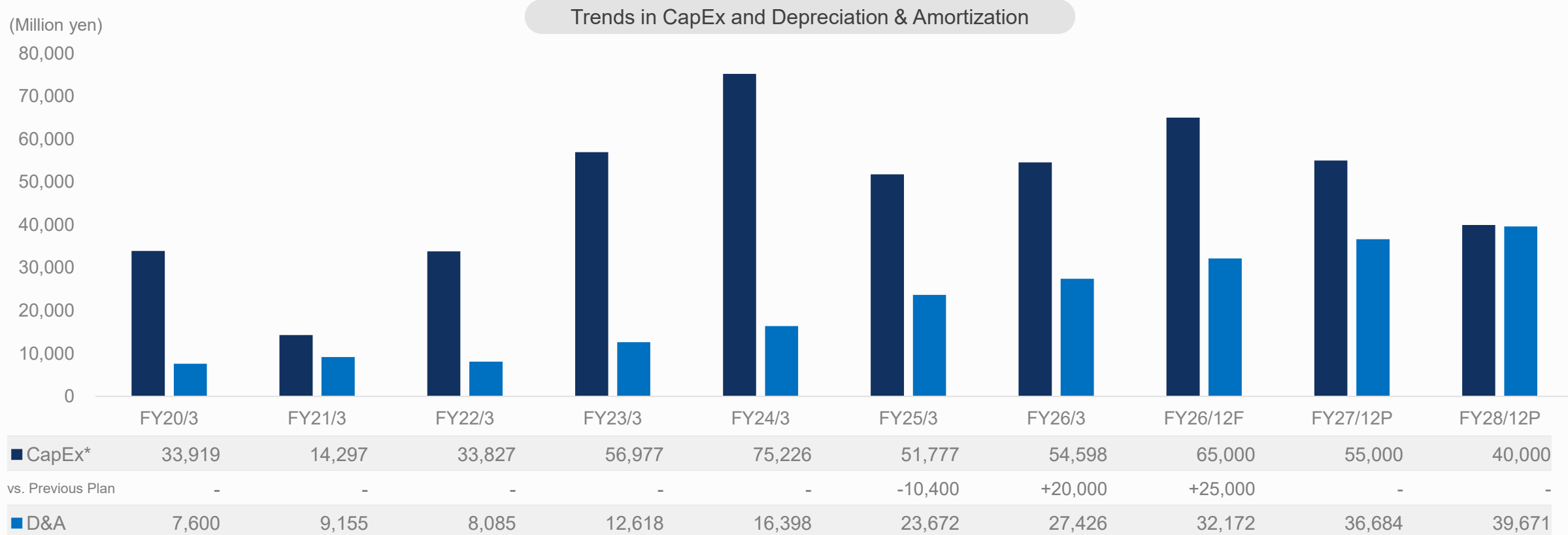
- Customer qualification and ramp-up at the Kulim Factory in Malaysia are progressing smoothly. The second factory (ceramics, quartz, and metal processing OEM) is scheduled to commence operations in 2026. Given strong demand and further capacity expansion requests from customers, additional expansion is under consideration.
- A new Beijing Factory (parts cleaning, metal processing OEM and ceramics) is being established to strengthen customer engagement.

Shareholder returns

- Plan to carry out share buybacks of up to ¥25.0bn over the period from FY26/12 through FY28/12.
- For FY26/12, an increased dividend is planned, with a full-year dividend of ¥200 per share (ordinary dividend: ¥150, special dividend: ¥50).

Capital Expenditure Plan and Other Initiatives

- Reflecting the establishment of the new Beijing Factory (parts cleaning, etc.), additional capacity investment in ceramics and other products, and further investment in the Malaysia Factory in response to growing semiconductor demand and customer requests, the CapEx plan for FY26/3–FY27/12 has been increased to ¥174.6bn.
- Group asset disposals of ¥50.0bn are planned during FY26/3–FY27/12 (unchanged from the previous plan).

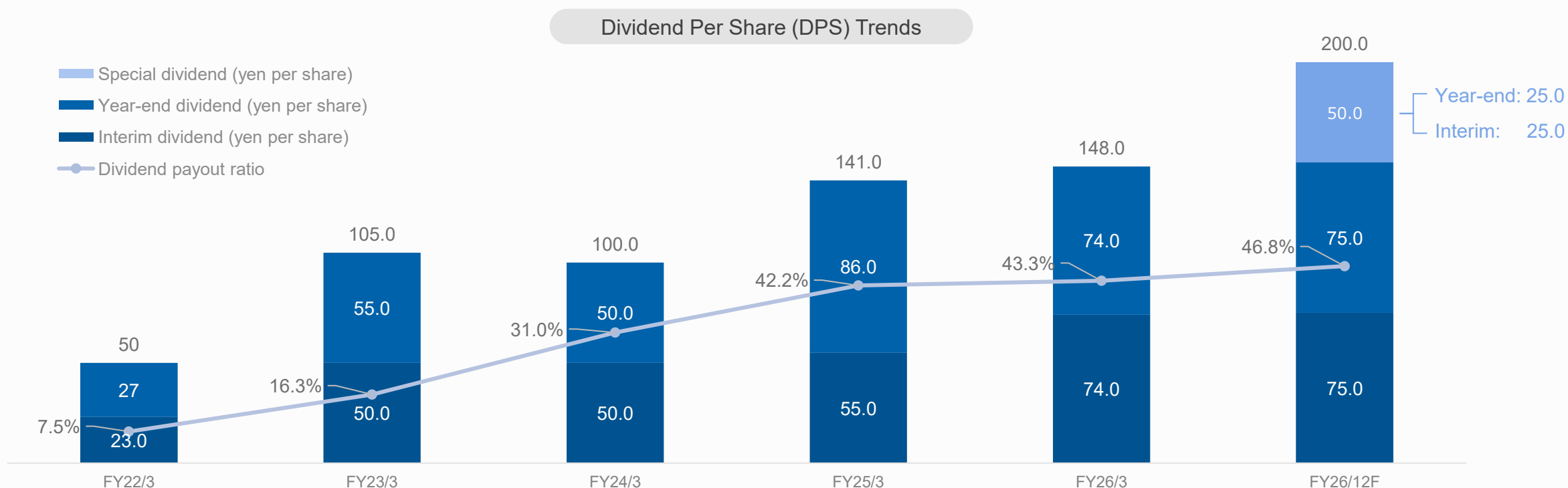


* Total acquisition cost of property, plant, and equipment and intangible assets

Shareholder Returns

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* For the interim dividend for FY26/12, the record date will be changed from September 30 to June 30, and the interim dividend will be paid based on the new record date.



Medium-Term Management Plan – Targets

► Long-term performance targets remain unchanged; we aim for early achievement.

Targeting net sales of **¥500bn** and profit attributable to owners of parent of **¥50bn** by **FY30/12**.



Appendix

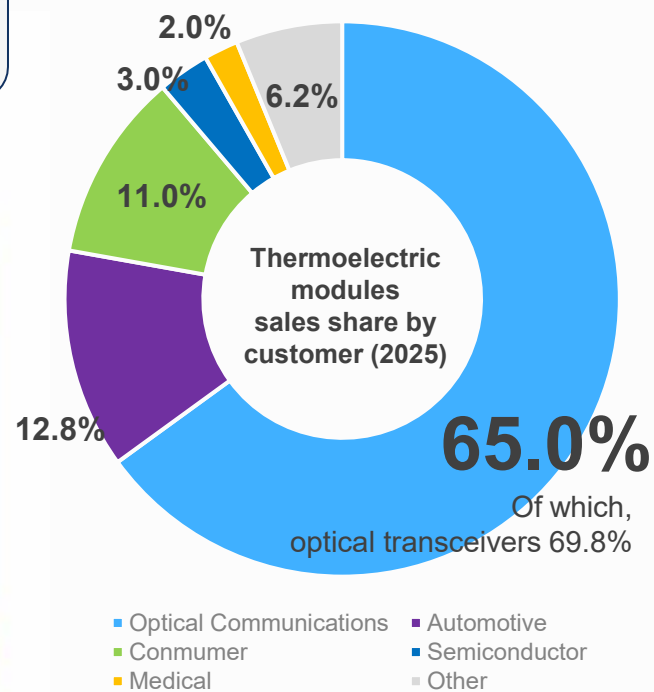
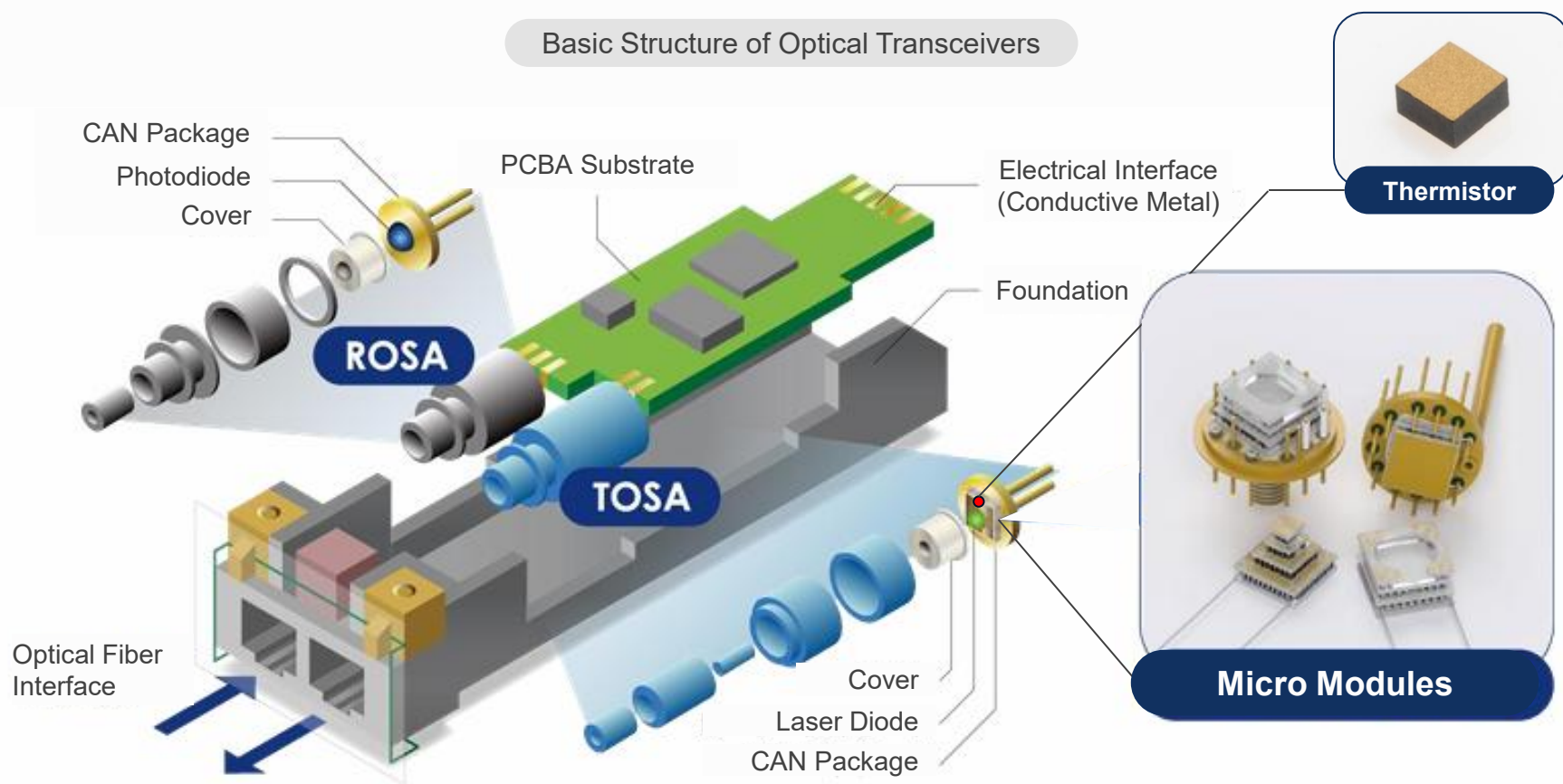
New Factory Launch Schedule

- ▶ As the new factories begin mass production and move into full-scale operation, their contribution to earnings is expected to become substantial, leading to an improvement in profit margins.

		Location	2025	2026	Now	2027	2028	2029	Assumed production capacity*
Power semiconductor substrates	China	Neijiang	Mass production			Full-scale operation			¥23bn
Power semiconductor substrates	Malaysia	Johor Bahru	Trial / Qualification			Mass production	Full-scale operation		¥11bn
Ceramics	Japan	Ishikawa 3		Tria / Qualification		Mass prod.	Full-scale operation		¥3bn
Ceramics / Silicon parts / CVD-SiC	China	Changshan 3	Trial / Qualification			Mass prod.	Full-scale operation		¥17bn
Quartz / Ceramics / Metal processing OEM	Malaysia	Kulim 1	Mass production			Full-scale operation			¥30bn
Quartz / Ceramics / Metal processing OEM	Malaysia	Kulim 2				Trial / Qualification	Mass production	Full-scale op.	¥28bn
Metal processing OEM	China	Changshan 4		Trial		Mass production	Full-scale operation		¥6bn
Parts cleaning	Japan	Kumamoto		Trial / Qualification		Mass production	Full-scale operation		¥2bn
Parts cleaning / Metal processing / Ceramics	China	Beijing					Trial / Qualification	Mass prod.	¥7bn
Parts cleaning	China	Shaoxing					Trial / Qualification	Mass prod.	¥17bn
Parts cleaning	China	Wuhan					Trial / Qualification	Mass prod.	¥2bn

* Assumed production capacity represents net sales assuming maximum production volume is sold.

- ▶ As generative AI advances and demand expands, data center investment is projected to reach ¥100tn by 2030.
- ▶ The Company has a high share of business with leading global optical transceiver manufacturers that produce high-capacity models (800G / 1.6T) used in generative AI servers, and sales of thermoelectric modules and thermistors (temperature sensors) are expected to increase.



Status of Chinese Subsidiaries (Listed Subsidiaries)

Business	Parts cleaning	Power semiconductor substrates	Silicon wafers	Quartz crucibles and silicon parts
Company name	Ferrotec (Anhui) Technology Development Co., Ltd.	Jiangsu Ferrotec Semiconductor Technology Co., Ltd.	Hangzhou Semiconductor Wafer Co., Ltd.	Ningxia Dunyuan Juxin Semiconductor Technology Corporation
Abbreviation	FTSVA	FLH	CCMC	FTNC
Ownership	52.4%		23.43%(Equity-method affiliate)	60.13%
Valuation*	Approx. RMB 40.2bn (approx. JPY 939.4B)		Approx. RMB 23.4bn (approx. JPY 547.2bn)	Approx. RMB 5.5bn (approx. JPY 129.4bn)
Equity-attributable amount	JPY 492.2bn		JPY 128.2bn	JPY 77.8bn
Planned new share issuance ratio	—		≥10%	≥10%
Listing market	Shenzhen Stock Exchange ChiNext		New Third Board (National Equities Exchange and Quotations)	—
Securities code	301297		874810	—
Status and outlook	Listed on Dec. 30, 2022	Became a subsidiary of FTSVA in Jul. 2025	Registered on Sep. 22, 2025	Listing application withdrawn in Jan. 2025 (re-application under consideration)

*As of May 15, 2025 (1 RMB = 23.33 JPY)

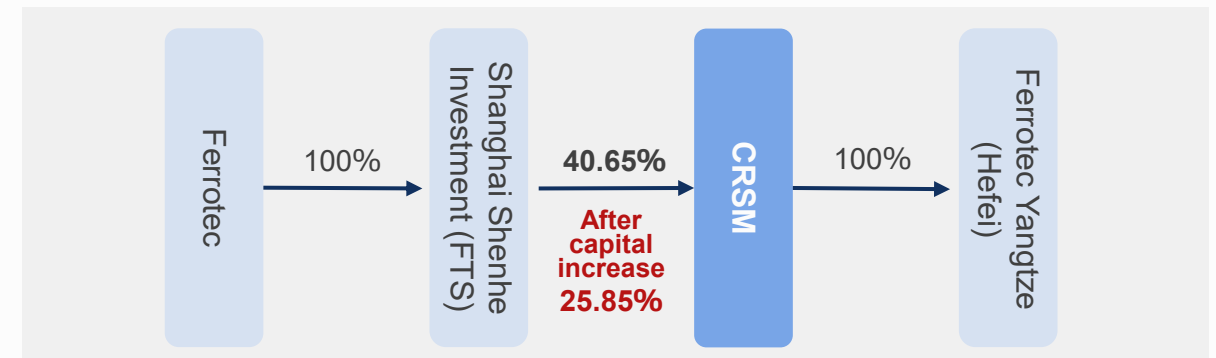
Change in Status of Wafer Reclaiming Business (CRSM) to Equity-Method Affiliate **Ferrotec**

- Anhui Changjiang Reclaim Semiconductor Material Co., Ltd. (CRSM), which operates the wafer reclaiming business, will conduct a capital increase in connection with the establishment of a new company and new factory in the Hefei area of China. As a result, CRSM is expected to be transferred from a consolidated subsidiary to an equity-method affiliate (expected from July 2026 onwards).
- This represents a growth investment in the wafer reclaiming business and is also intended to improve profitability through business portfolio selection and concentration.

Overview of New Company and Factory

Company name	Ferrotec Yangtze (Hefei) Semiconductor Material Co., Ltd.
Investment amount	<p>RMB 2bn (approx. JPY 46.6bn) *1RMB = JPY 23.31</p> <ul style="list-style-type: none"> • New factory (Hefei): RMB 1.6bn (approx. JPY 37.3bn) • Capacity expansion at Tongling Factory: RMB 0.4bn (approx. JPY 9.3bn) <p>↳ RMB 1.4bn will be financed through equity investment and RMB 0.6bn through loans.</p>
Total floor area	Approx. 80,000m ²
Schedule	<p>Start of construction: May 2026</p> <p>Building completion: March 2027</p> <p>Equipment installation: September 2027</p> <p>Scheduled start of operations: December 2027</p>

Capital Relationship with Ferrotec



Performance of CRSM (Wafer Reclaiming)

(Millions of yen)	FY2023/3	FY2024/3	FY2025/3
Net sales	1,501	1,774	2,869
Operating profit	-1,251	-1,329	-1,483
Ordinary profit	-864	-816	-1,267
Profit attributable to owners of parent	-260	-282	-515

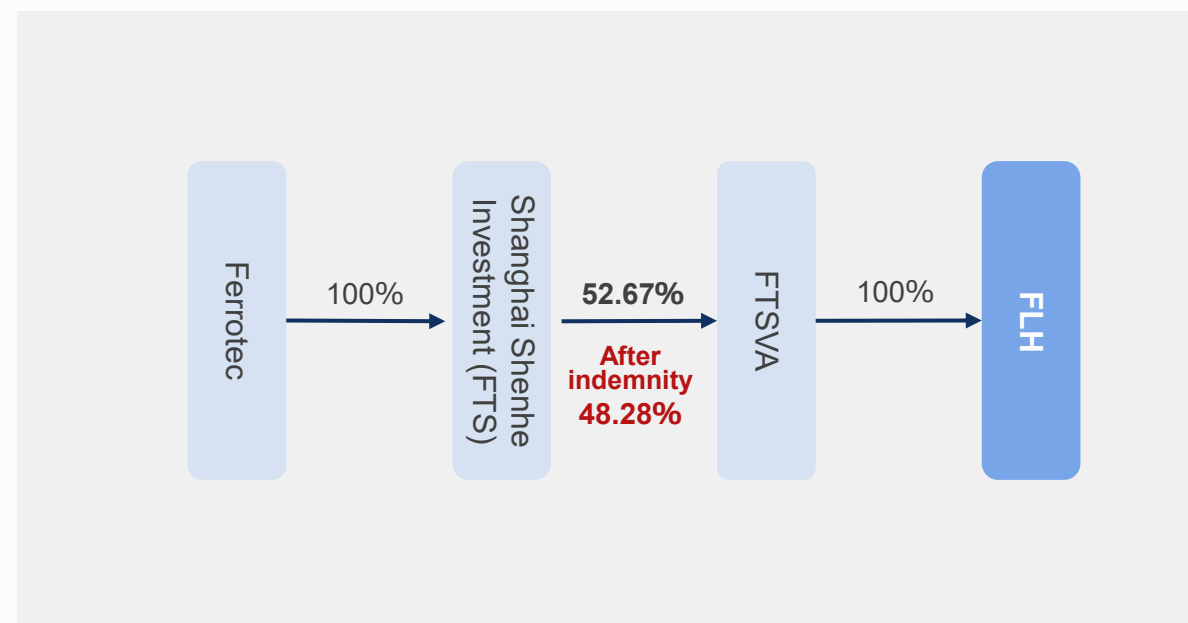
Profit Indemnity for FLH (Power Semiconductor Substrates)

- As FLH's actual results fell below the committed net profit amount, FTSVA will repurchase and cancel the FTSVA shares held by FTS.*1
- The share repurchase and cancellation themselves constitute a transfer of shares between consolidated subsidiaries. As the control relationship remains unchanged, there is no impact on consolidated profit or loss.

Overview of Profit Indemnity

(Millions of RMB; unless otherwise stated)	FY2025*2
Actual net profit (results)	124.2
Committed net profit	285.2 (FY26 : 342.1、 FY27 : 414.2、 Total in 3 years : 1,041.5)
Amount to be compensated	1,028
Decrease in FTS's ownership ratio	-4.39 pp

Capital Relationship with Ferrotec



*1. Refer to the release titled "(Progress of Disclosed Matter) Notice of Acquisition and Cancellation of Treasury Shares of the Company's Chinese Subsidiary (FTSVA) pursuant to the Profit Indemnity Agreement" disclosed on April 30, 2026

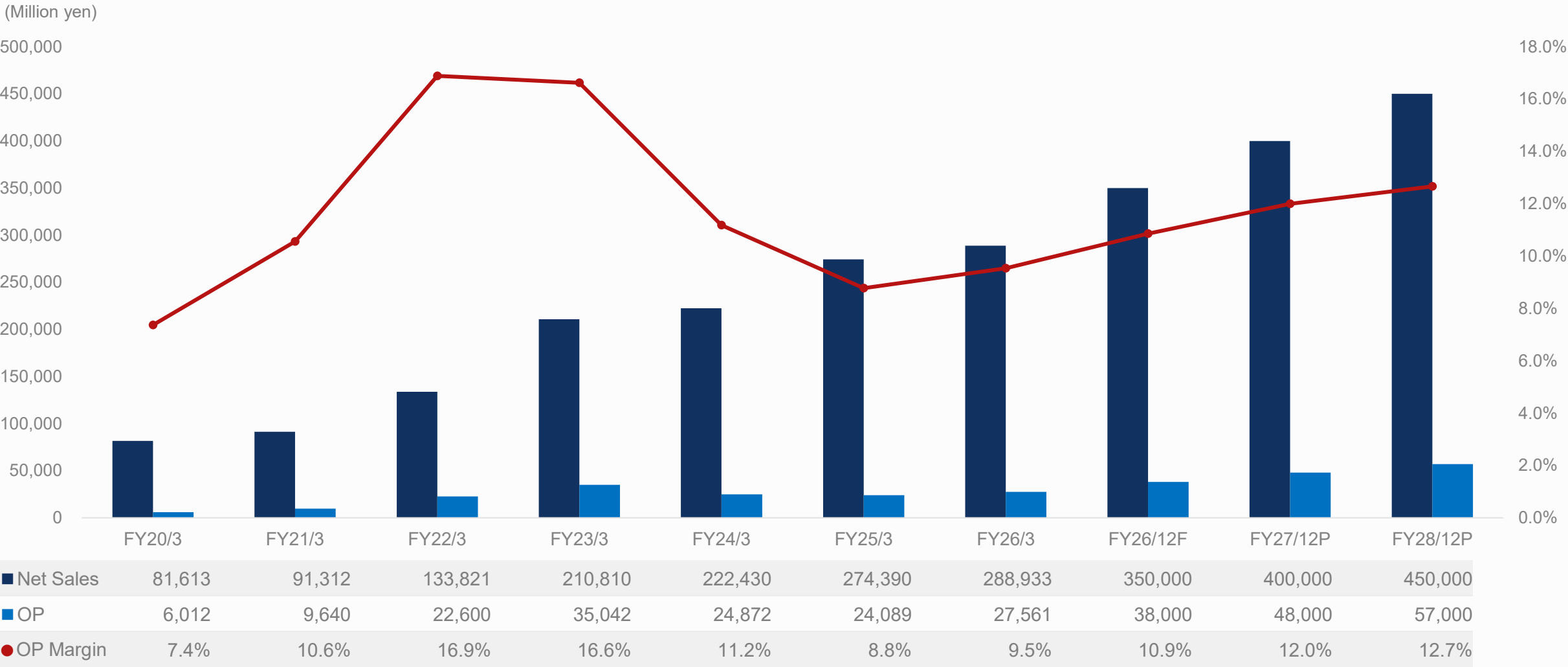
*2. Fiscal year: January–December

Q4 Consolidated Financial Summary

(Million yen; unless otherwise stated)	FY26/3 Q4	FY26/3 Q3	QoQ change		FY25/3 Q4	YoY change	
	Amount	Amount	Amount	%	Amount	Amount	%
Net sales	77,287	70,665	6,622	9.4%	72,025	5,262	7.3%
Cost of sales	57,874	49,541	8,332	6.8%	55,146	2,727	4.9%
Gross profit	19,413	21,123	-1,709	-8.1%	16,878	2,534	15.0%
SG&A expenses	13,691	13,616	74	0.6%	12,485	1,206	9.7%
Operating profit	5,721	7,506	-1,784	-23.8%	4,393	1,328	30.2%
Ordinary profit	6,426	6,713	-286	-4.3%	5,041	1,385	27.5%
Profit attributable to non-controlling interests	871	773	97	12.6%	591	280	47.4%
Profit attributable to owners of parent	4,740	3,837	903	23.5%	3,080	1,660	53.9%
Depreciation and amortization	7,490	6,685	805	12.0%	6,376	1,114	17.5%
Exchange rate (average during the period)	USD/JPY	¥149.78	¥147.78		¥152.24		
	RMB/JPY	¥20.87	¥20.48		¥21.12		



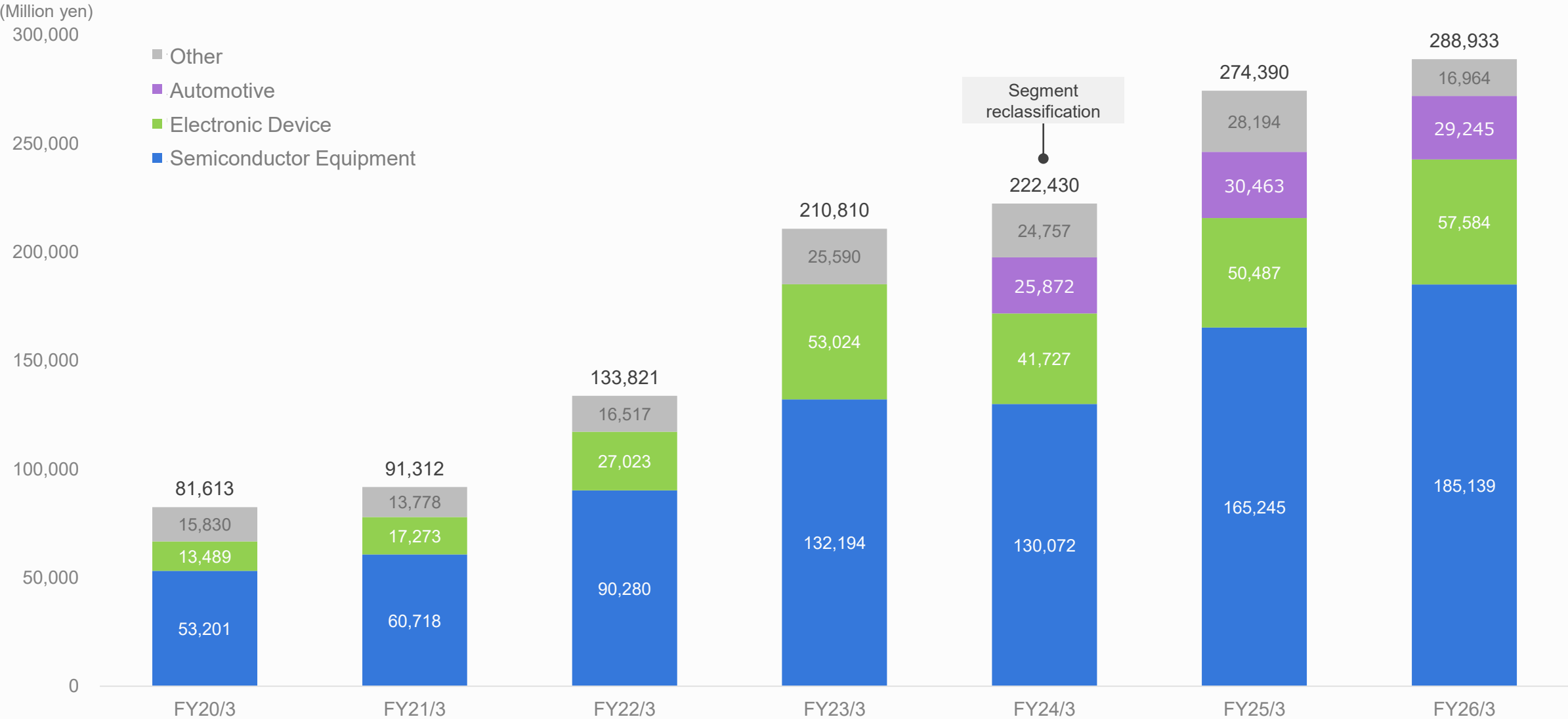
Performance Trends



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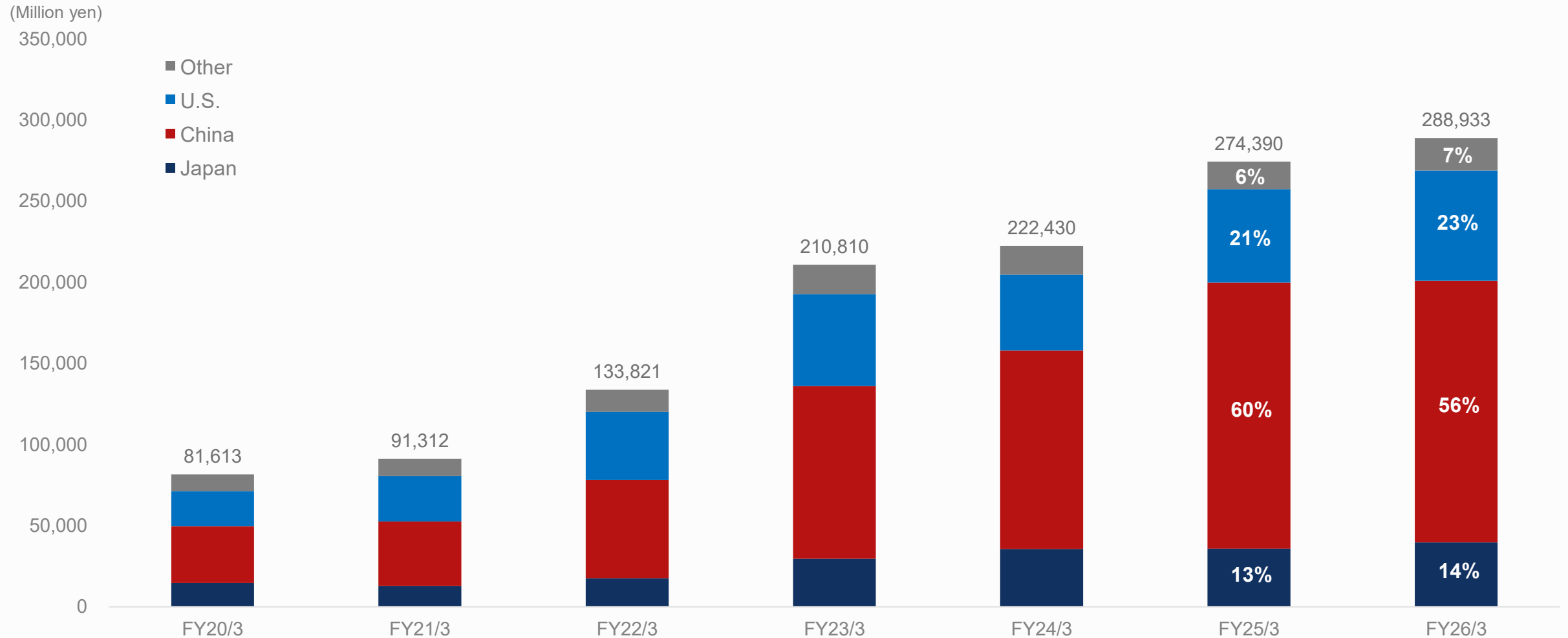


Sales by Segment



Sales by Region

➤ Regions are classified based on the location of the revenue-recognizing entity.



Company Overview

Company name	Ferrotec Corporation
Date established	September 27, 1980
Representatives	Xe Xian Han, Representative Director, President and Group CEO
Headquarters	5F Nihonbashi Plaza Building, 2-3-4, Nihonbashi, Chuo-ku, Tokyo 103-0027, Japan
Stock listing	TSE Standard Market (Securities code: 6890)
Consolidated net sales	288,933 million yen
Share capital	29,549 million yen
Employees	Consolidated: 16,858 Parent: 519
Group companies	Consolidated subsidiaries: 80 Equity-method affiliates: 13

(FY2026/3)

Business Segments

1. Semiconductor Equipment business

- Vacuum feedthroughs, material products for SPEs (quartz, ceramics, silicon parts, CVD-SiC), quartz crucibles, silicon wafers, reclaim wafers, contract manufacturing & machine assembly, process tools, parts cleaning, etc.

2. Electronic Device business

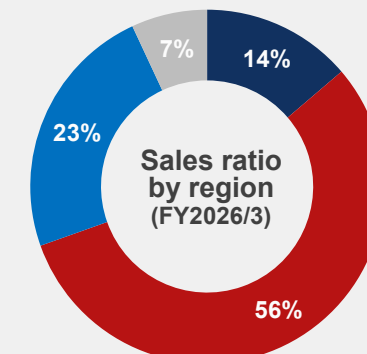
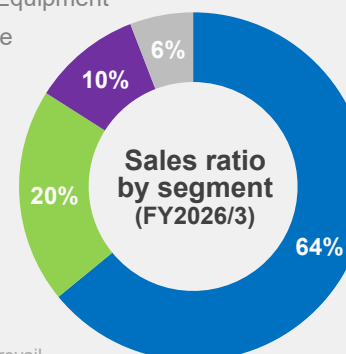
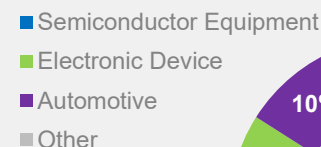
- Thermoelectric modules, power semiconductor substrates, thermistor sensors, ferrofluids

3. Automotive business

- Thermoelectric modules, power semiconductor substrates, thermistor sensors

4. Other businesses

- Industrial blades & cutters, industrial cleaning equipment, Ingot pulling equipment, etc.



Product Lineup – One-Stop Solutions for Semiconductor Manufacturing



Semiconductor Equipment Segment



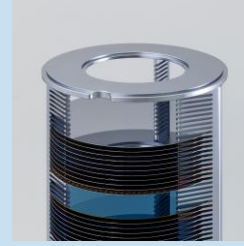
Vacuum feedthroughs



Metal processing OEM



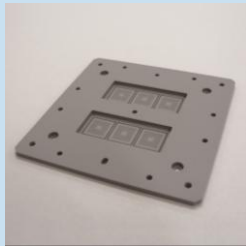
Quartz



Silicon parts



Fine ceramics



Machinable ceramics



CVD-SiC



Parts cleaning



EB guns



Crucibles



Reclaim wafers



Silicon wafers*

*Non-consolidated

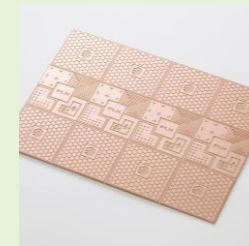
Electronic Device Segment



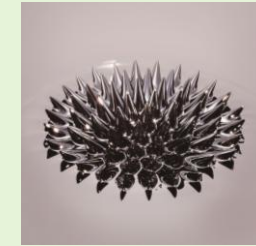
Thermoelectric modules



Chillers



Power semiconductor substrates



Ferrofluid

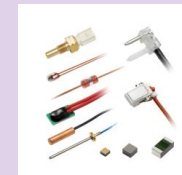


Thermistor sensors

Automotive Segment



Power semiconductor substrates



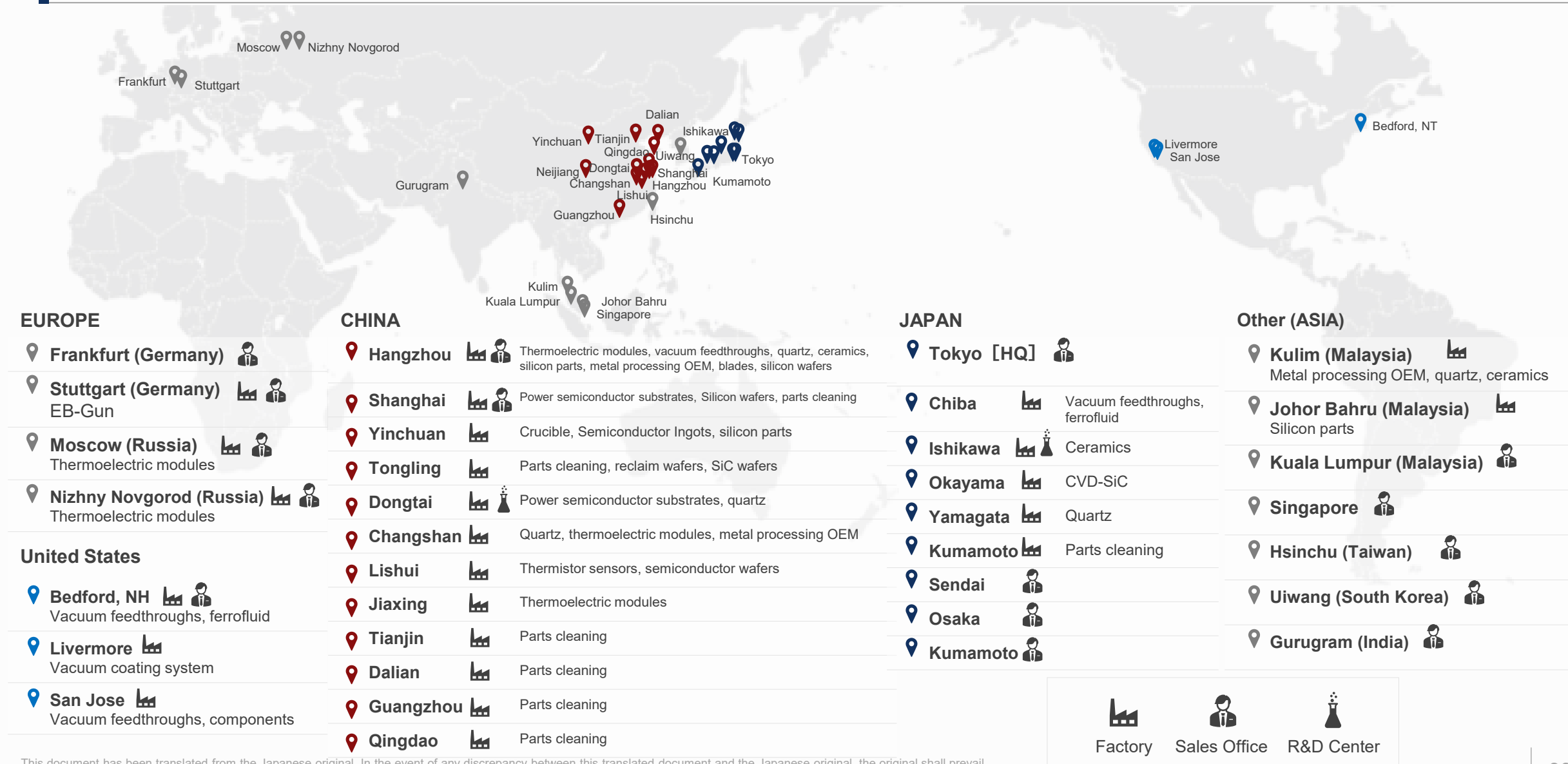
Thermistor sensors

Other



Blades, etc.

Ferrotec Group Locations



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English



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- Actual results may differ materially from those projected due to various factors. Factors that may affect performance include, but are not limited to, international conditions, economic conditions, supply and demand trends for products, raw material prices and market conditions, and foreign exchange rates.
- Figures in this material have been rounded to the nearest million yen or hundred million yen. Accordingly, figures may not exactly match those disclosed in financial statements such as the Summary of Financial Results (Kessan Tanshin) or Annual Securities Reports.
- Quantitative targets and other forward-looking information in this material are intended solely to illustrate medium- to long-term strategies and vision, and do not constitute earnings forecasts. The Company assumes no obligation to update such information.
- For official earnings forecasts, please refer to the Summary of Financial Results (Kessan Tanshin) disclosed in accordance with Tokyo Stock Exchange regulations.